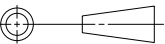


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
	SEE SHEET 1			

PACKAGE DIMENSIONS					
X1 DESIGNATOR	X1 PACKAGE WIDTH ±30μm	X2 DESIGNATOR	X2 PACKAGE LENGTH ±30μm	X3 DESIGNATOR	X3 PACKAGE HEIGHT ±75μm
A	777	A	777	A	500
B	803	B	803		
C	828	C	828		
D	853	D	853		
E	879	E	879		
F	904	F	904		
G	930	G	930		
H	955	H	955		
J	980	J	980		
K	1006	K	1006		
L	1031	L	1031		
M	1057	M	1057		
N	1082	N	1082		
P	1107	P	1107		
Q	1133	Q	1133		
R	1158	R	1158		
S	1184	S	1184		
T	1209	T	1209		
U	1234	U	1234		
V	1260	V	1260		
W	1285	W	1285		
X	1311	X	1311		
Y	1336	Y	1336		
2	1361	2	1361		
3	1387	3	1387		
4	1412	4	1412		
5	1438	5	1438		
6	1463	6	1463		

APPROVALS		DATE	National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DRAWN	MARTA SUCHY	02/13/2002			
DFTG. CHK.	THANH LEQUANG	02/13/2002			
ENGR. CHK.	VIVEK ARORA	02/13/2002			
			THIN MICRO SMD, 4 BUMP, 0.5mm PITCH		
PROJECTION  MM		SCALE	SIZE	DRAWING NUMBER	REV
		NTS	B	(SC)MKT-TPA04XXX	A
FORMERLY: N/A					SHEET 2 of 2